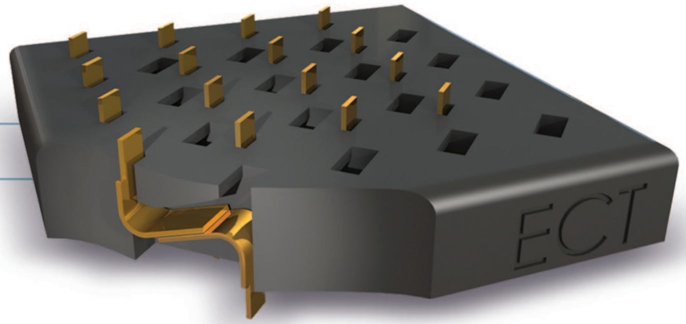
sliver

low profile, high value



Design

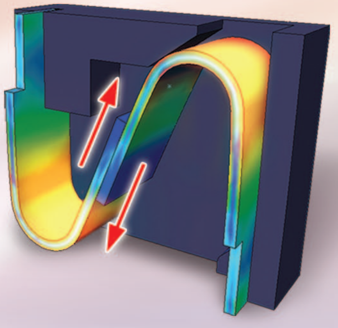
Innovative dual contact construction; designed per customer specifications

Application Highlights

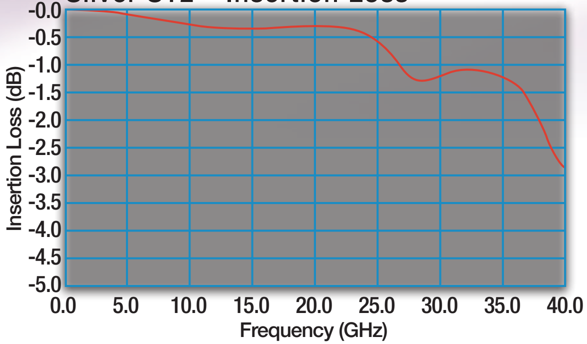
Efficient use of Z axis makes the Sliver ideal for low profile and difficult packaging applications

Features & Benefits

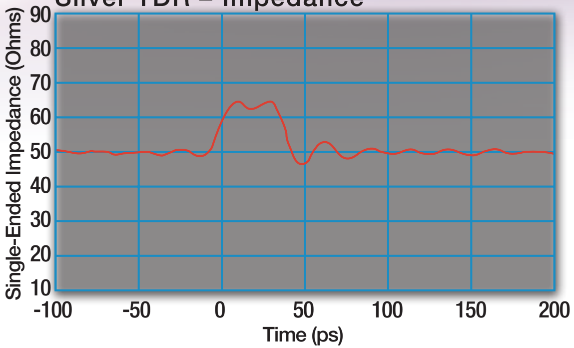
- Patented low profile, high compliance contact
  - Low cost, ideal for high volume applications
  - Can achieve compliance equaling 50% of its overall length
  - Less than 1.0mm compressed height
  - Superior conductive path with low inductance
  - Allows for tight pitch spacing; down to .5mm inline and .65mm array
- Single piece molded housing
  - Lowers tooling costs
- Patented sliding action
  - Provides maximum compliance while maintaining the lowest Z-Height package in the industry
  - Mitigates internal stresses



Sliver S12 – Insertion Loss



Sliver TDR – Impedance



Patent Numbers 7,695,286; 5,865,641; 5,801,544 and other Patents Pending.